

Electrical Characteristics (T_J=25℃ unless otherwise noted)

Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC PARAMETERS							
BV _{DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V				1	μА
			T _J =55℃			5	μΛ
I_{GSS}	Gate-Body leakage current	V_{DS} =0V, V_{GS} = ±16V				10	uA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS} I_{D}=250\mu A$		1	1.32	1.8	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V_{GS} =10V, I_D =4.2A			43	52	mΩ
			T _J =125℃		58	74	
		V_{GS} =4.5V, I_D =2A			59	75	mΩ
g _{FS}	Forward Transconductance	V_{DS} =5V, I_D =4.2A			8.5		S
V_{SD}	Diode Forward Voltage	I _S =1A,V _{GS} =0V			0.77	1	V
Is	Maximum Body-Diode Continuous Curr	rent				1.8	Α
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz			269	340	pF
C _{oss}	Output Capacitance				65		pF
C _{rss}	Reverse Transfer Capacitance				41		pF
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz			1	1.5	Ω
SWITCHII	NG PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =4.2A			5.7	7.2	nC
Q _g (4.5V)	Total Gate Charge				3		nC
Q_{gs}	Gate Source Charge				1.37		nC
Q_{gd}	Gate Drain Charge				0.65		nC
t _{D(on)}	Turn-On DelayTime	V_{GS} =10V, V_{DS} =15V, R_L =3.6 Ω , R_{GEN} =3 Ω			2.6	3.8	ns
t _r	Turn-On Rise Time				5.5	8	ns
t _{D(off)}	Turn-Off DelayTime				15.2	23	ns
t _f	Turn-Off Fall Time				3.7	5.5	ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =4.2A, dI/dt=100A/μ	ıs		15.5	21	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I _F =4.2A, dI/dt=100A/μs			7.1		nC

A: The value of R_{0JA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C. The value in any given application depends on the user's specific board design.

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B: Repetitive rating, pulse width limited by junction temperature.

C. The R $_{\theta JA}$ is the sum of the thermal impedence from junction to lead R $_{\theta JL}$ and lead to ambient.

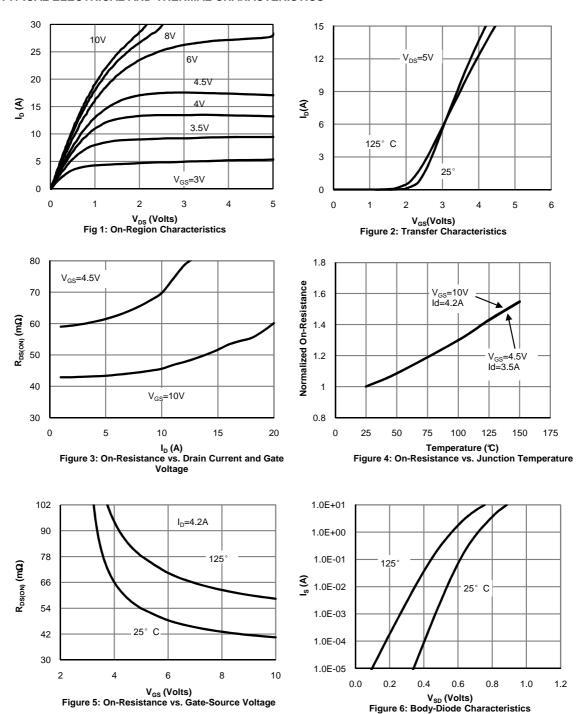
D. The static characteristics in Figures 1 to 6 are obtained using <300 µs pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in ² FR-4 board with 2oz. Copper, in a still air environment with T _A=25° C. The SOA curve provides a single pulse rating.

F.The current rating is based on the t≤10s thermal resistance rating.

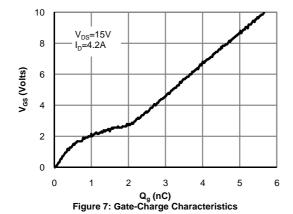


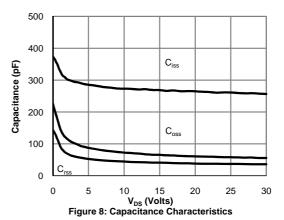
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

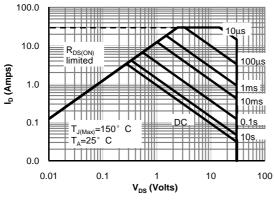




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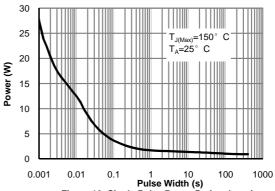


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

